

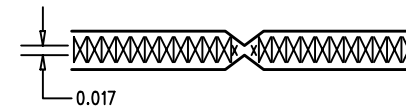
SHOWN FROM COMPONENT SIDE

REVISIONS			
REV	DESCRIPTION	APPR	DATE
A	PROTOTYPE RELEASE		


SIZE	QTY	SYM	PLTD
0.07	2	+	NPLTD
0.035	36	×	PLTD
0.015	138	□	PLTD
0.094	9	◇	PLTD
0.055	15	⊗	PLTD
0.125	4	⊠	PLTD

NOTES : Unless Otherwise Specified

1. MATERIAL : FR4 OR EQUIVALENT EPOXY, 2 OZ. COPPER CLAD
THICKNESS .062 +/- .006 TOTAL OF 4 LAYERS.
2. FINISH : ALL PLATED HOLES .001 MIN. / .0015 MAX. COPPER PLATE
ELECTRODEPOSITED TIN-LEAD COMPOSITION
BEFORE REFLOW , SOLDER MASK OVER BARE COPPER (SMOBC).
3. SOLDER MASK : BOTH SIDES USING LPI OR EQUIVALENT.
4. SILKSCREEN : USING WHITE NON-CONDUCTIVE EPOXY INK.
5. UNUSED SMD COMPONENTS SHOULD BE FREE OF SOLDER.
6. SCORING:



7. PLEASE LOOK AT THE READ ME FILE FOR THE OTHER REQUIREMENTS.

APPROVALS			 LINEAR TECHNOLOGY 1630 McCarthy Blvd. Milpitas, CA 95035 PH: (408)432-1900	
	INIT	DATE		
DRAWN			TITLE: FABRICATION DRAWING 3V, 16-BIT 150KSPS ADC	
CHECK				
DESIGN	KIM T.	06-25-02		
ENGR	GUY H.	06-25-02		
			SIZE	REV.
			A	A
			DEMO	
			DC547A * LTC1864LAIMS8	
SCALE = NONE			DES- 0000	SHT 1 of 1